

# STARPOWER

SEMICONDUCTOR

**IGBT**

## GD2400SGX170C3SN

**1700V/2400A 1 in one-package**

### General Description

STARPOWER IGBT Power Module provides ultrafast switching speed as well as short circuit ruggedness.

It's designed for the applications such as general inverters and UPS.

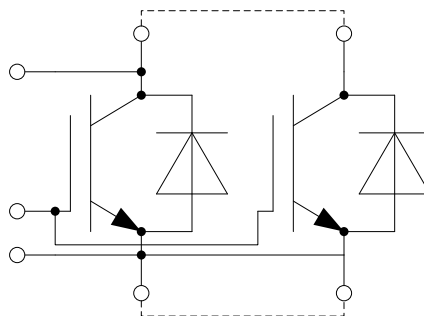
### Features

- Low  $V_{CE(sat)}$  Trench IGBT technology
- 10 $\mu$ s short circuit capability
- $V_{CE(sat)}$  with positive temperature coefficient
- Maximum junction temperature 175°C
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology

### Typical Applications

- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply

### Equivalent Circuit Schematic



**Absolute Maximum Ratings**  $T_C=25^{\circ}\text{C}$  unless otherwise noted**IGBT**

| Symbol    | Description  | Value    | Unit |
|-----------|--|----------|------|
| $V_{CES}$ | Collector-Emitter Voltage                                | 1700     | V    |
| $V_{GES}$ | Gate-Emitter Voltage                                     | $\pm 20$ | V    |
| $I_C$     | Collector Current @ $T_C=100^{\circ}\text{C}$            | 2400     | A    |
| $I_{CM}$  | Pulsed Collector Current $t_p=1\text{ms}$                | 4800     | A    |
| $P_D$     | Maximum Power Dissipation @ $T_{vj}=175^{\circ}\text{C}$ | 14.42    | kW   |

**Diode**

| Symbol    | Description                                    | Value | Unit |
|-----------|--|-------|------|
| $V_{RRM}$ | Repetitive Peak Reverse Voltage                | 1700  | V    |
| $I_F$     | Diode Continuous Forward Current               | 2400  | A    |
| $I_{FM}$  | Diode Maximum Forward Current $t_p=1\text{ms}$ | 4800  | A    |

**Module**

| Symbol      | Description   | Value       | Unit               |
|-------------|---|-------------|--------------------|
| $T_{vjmax}$ | Maximum Junction Temperature                          | 175         | $^{\circ}\text{C}$ |
| $T_{vjop}$  | Operating Junction Temperature                        | -40 to +150 | $^{\circ}\text{C}$ |
| $T_{STG}$   | Storage Temperature Range                             | -40 to +125 | $^{\circ}\text{C}$ |
| $V_{ISO}$   | Isolation Voltage RMS, $f=50\text{Hz}, t=1\text{min}$ | 4000        | V                  |

**IGBT Characteristics**  $T_C=25^{\circ}\text{C}$  unless otherwise noted

| Symbol        | Parameter                               | Test Conditions  | Min.   | Typ. | Max. | Unit     |    |
|---------------|---|--|--|------|------|----------|----|
| $V_{CE(sat)}$ | Collector to Emitter Saturation Voltage | $I_C=2400A, V_{GE}=15V, T_{vj}=25^\circ C$   |  | 1.85 | 2.30 | V        |    |
|               |   | $I_C=2400A, V_{GE}=15V, T_{vj}=125^\circ C$  |  | 2.25 |      |          |    |
|               |   | $I_C=2400A, V_{GE}=15V, T_{vj}=150^\circ C$  |  | 2.30 |      |          |    |
| $V_{GE(th)}$  | Gate-Emitter Threshold Voltage          | $I_C=60.0mA, V_{CE}=V_{GE}, T_{vj}=25^\circ C$   | 5.6  | 6.2  | 6.8  | V        |    |
| $I_{CES}$     | Collector Cut-Off Current               | $V_{CE}=V_{CES}, V_{GE}=0V, T_{vj}=25^\circ C$   |  |      | 5.0  | mA       |    |
| $I_{GES}$     | Gate-Emitter Leakage Current            | $V_{GE}=V_{GES}, V_{CE}=0V, T_{vj}=25^\circ C$   |  |      | 400  | nA       |    |
| $R_{Gint}$    | Internal Gate Resistance                |  |  | 1.06 |      | $\Omega$ |    |
| $C_{ies}$     | Input Capacitance                       |  |  | 285  |      | nF       |    |
| $C_{res}$     | Reverse Transfer Capacitance            | $V_{CE}=25V, f=1MHz, V_{GE}=0V$  |  | 7.1  |      | nF       |    |
| $Q_G$         | Gate Charge                             | $V_{GE}=-15...+15V$  |  | 23.5 |      | $\mu C$  |    |
| $t_{d(on)}$   | Turn-On Delay Time                      | $V_{CC}=900V, I_C=2400A, R_{Gon}=1.0\Omega, R_{Goff}=1.5\Omega, V_{GE}=-10/+15V, L_S=40nH, T_{vj}=25^\circ C$  |  | 996  |      | ns       |    |
| $t_r$         | Rise Time                               |  |  | 403  |      | ns       |    |
| $t_{d(off)}$  | Turn-Off Delay Time                     |  |  | 1756 |      | ns       |    |
| $t_f$         | Fall Time                               |  |  | 242  |      | ns       |    |
| $E_{on}$      | Turn-On Switching Loss                  |  |  | 1534 |      | mJ       |    |
| $E_{off}$     | Turn-Off Switching Loss                 |  |  | 990  |      | mJ       |    |
| $t_{d(on)}$   | Turn-On Delay Time                      |  | $V_{CC}=900V, I_C=2400A, R_{Gon}=1.0\Omega, R_{Goff}=1.5\Omega, V_{GE}=-10/+15V, L_S=40nH, T_{vj}=125^\circ C$ |      | 1287 |          | ns |
| $t_r$         | Rise Time                               |  |  |      | 595  |          | ns |
| $t_{d(off)}$  | Turn-Off Delay Time                     |  |  |      | 2282 |          | ns |
| $t_f$         | Fall Time                               |  |  |      | 279  |          | ns |
| $E_{on}$      | Turn-On Switching Loss                  |  |  | 2670 |      | mJ       |    |
| $E_{off}$     | Turn-Off Switching Loss                 |  |  | 1200 |      | mJ       |    |
| $t_{d(on)}$   | Turn-On Delay Time                      | $V_{CC}=900V, I_C=2400A, R_{Gon}=1.0\Omega, R_{Goff}=1.5\Omega, V_{GE}=-10/+15V, L_S=40nH, T_{vj}=150^\circ C$ |  |      | 1380 |          | ns |
| $t_r$         | Rise Time                               |  |  |      | 657  |          | ns |
| $t_{d(off)}$  | Turn-Off Delay Time                     |  |  |      | 2449 |          | ns |
| $t_f$         | Fall Time                               |  |  |      | 292  |          | ns |
| $E_{on}$      | Turn-On Switching Loss                  |  |  | 2960 |      | mJ       |    |
| $E_{off}$     | Turn-Off Switching Loss                 |  |  | 1250 |      | mJ       |    |
| $I_{SC}$      | SC Data                                 |  | $t_p \leq 10\mu s, V_{GE}=15V, T_{vj}=150^\circ C, V_{CC}=1000V, V_{CEM} \leq 1700V$                           |      | 9600 |          | A  |

### Diode Characteristics $T_C=25^\circ C$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|--------|-----------|-----------------|------|------|------|------|
|--------|-----------|-----------------|------|------|------|------|

|           |                               |   |      |      |         |
|-----------|-------------------------------|---|------|------|---------|
| $V_F$     | Diode Forward Voltage         | $I_F=2400A, V_{GE}=0V, T_{vj}=25^{\circ}C$  | 1.80 | 2.25 | V       |
|           |                               | $I_F=2400A, V_{GE}=0V, T_{vj}=125^{\circ}C$   | 1.90 |      |         |
|           |                               | $I_F=2400A, V_{GE}=0V, T_{vj}=150^{\circ}C$   | 1.95 |      |         |
| $Q_r$     | Recovered Charge              |   | 429  |      | $\mu C$ |
| $I_{RM}$  | Peak Reverse Recovery Current | $V_R=900V, I_F=2400A,$<br>$-di/dt=5000A/\mu s, V_{GE}=-10V,$<br>$L_S=40nH, T_{vj}=25^{\circ}C$  | 871  |      | A       |
| $E_{rec}$ | Reverse Recovery Energy       |   | 186  |      | mJ      |
| $Q_r$     | Recovered Charge              |   | 661  |      | $\mu C$ |
| $I_{RM}$  | Peak Reverse Recovery Current | $V_R=900V, I_F=2400A,$<br>$-di/dt=3300A/\mu s, V_{GE}=-10V,$<br>$L_S=40nH, T_{vj}=125^{\circ}C$ | 795  |      | A       |
| $E_{rec}$ | Reverse Recovery Energy       |   | 250  |      | mJ      |
| $Q_r$     | Recovered Charge              |   | 658  |      | $\mu C$ |
| $I_{RM}$  | Peak Reverse Recovery Current | $V_R=900V, I_F=2400A,$<br>$-di/dt=3000A/\mu s, V_{GE}=-10V,$<br>$L_S=40nH, T_{vj}=150^{\circ}C$ | 757  |      | A       |
| $E_{rec}$ | Reverse Recovery Energy       |   | 270  |      | mJ      |

### Module Characteristics $T_C=25^{\circ}C$ unless otherwise noted

| Symbol        | Parameter                                | Min. | Typ. | Max. | Unit       |
|---------------|--|------|------|------|------------|
| $L_{CE}$      | Stray Inductance                         |      | 9    |      | nH         |
| $R_{CC'+EE'}$ | Module Lead Resistance, Terminal to Chip |      | 0.18 |      | m $\Omega$ |
| $R_{thJC}$    | Junction-to-Case (per IGBT)              |      |      | 10.4 | K/kW       |
|               | Junction-to-Case (per Diode)             |      |      | 19.8 |            |
| $R_{thCH}$    | Case-to-Heatsink (per IGBT)              |      | 9.2  |      | K/kW       |
|               | Case-to-Heatsink (per Diode)             |      | 17.5 |      |            |
|               | Case-to-Heatsink (per Module)            |      | 6.0  |      |            |
| M             | Terminal Connection Torque, Screw M4     | 1.8  |      | 2.1  | N.m        |
|               | Terminal Connection Torque, Screw M8     | 8.0  |      | 10   |            |
|               | Mounting Torque, Screw M6                | 4.25 |      | 5.75 |            |
| G             | Weight of Module                         |      | 1300 |      | g          |

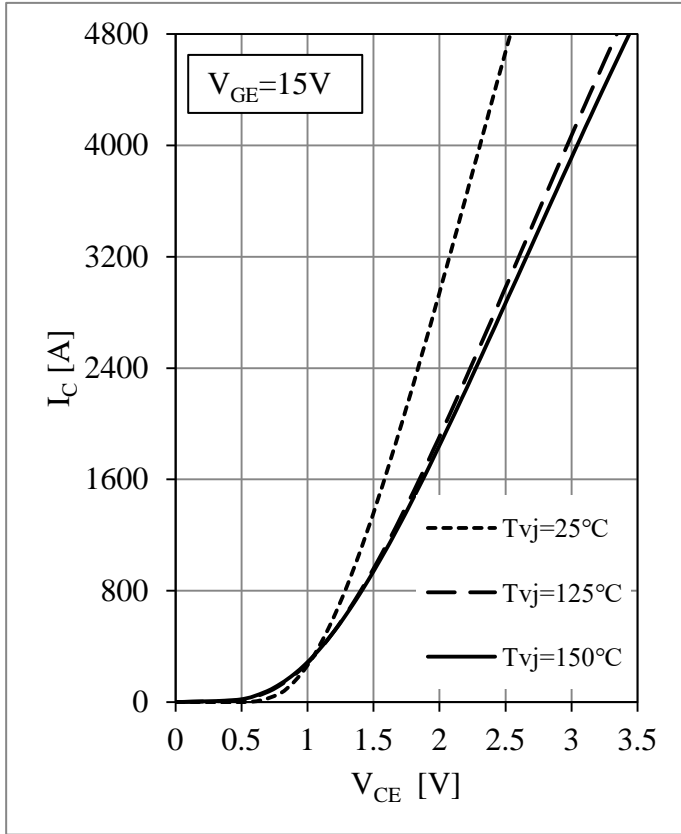


Fig 1. IGBT Output Characteristics

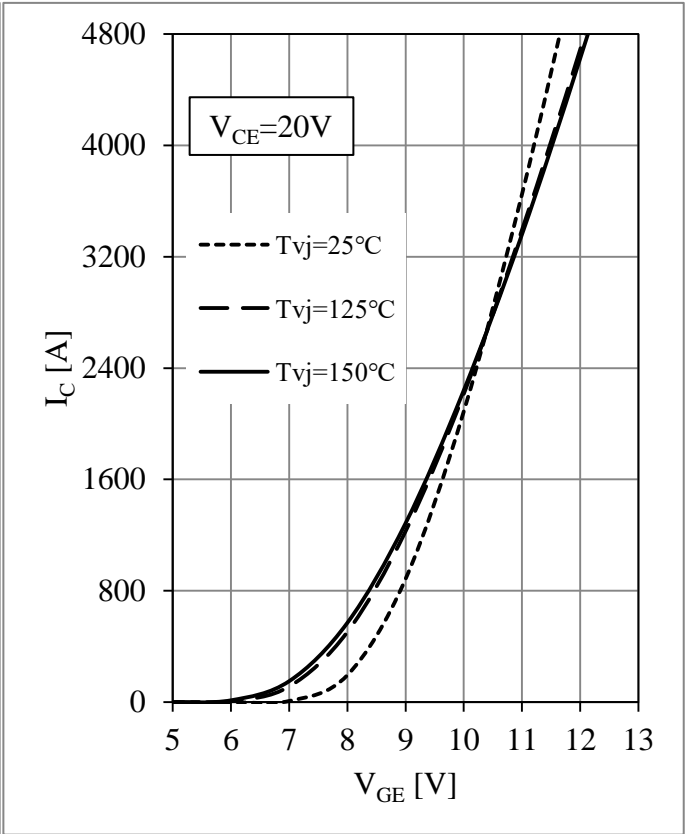


Fig 2. IGBT Transfer Characteristics

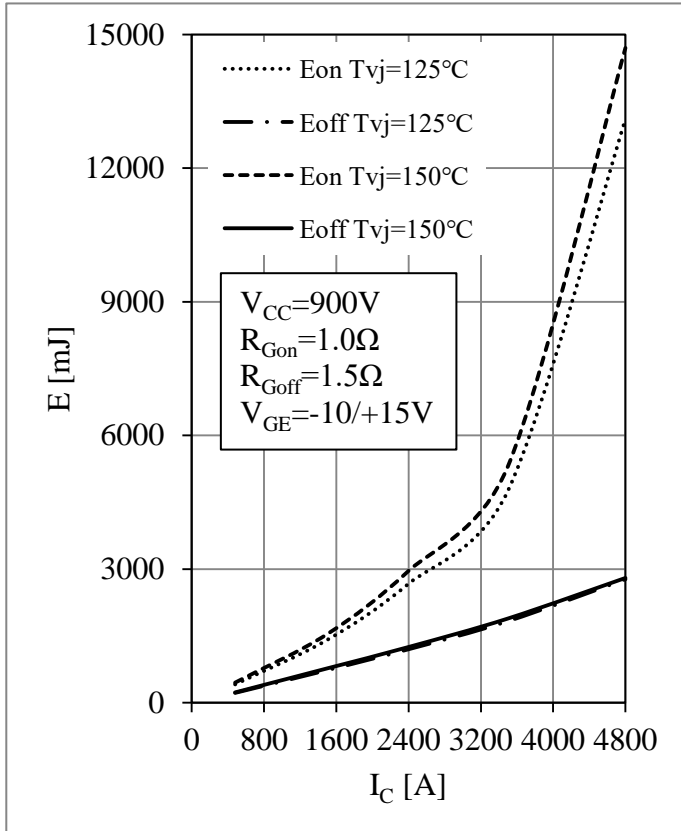


Fig 3. IGBT Switching Loss vs.  $I_c$

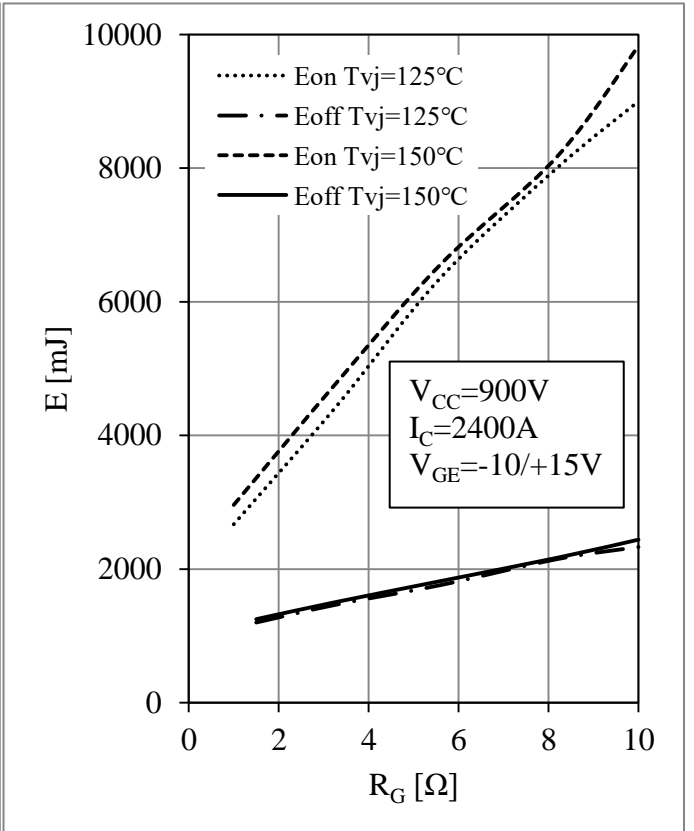


Fig 4. IGBT Switching Loss vs.  $R_g$

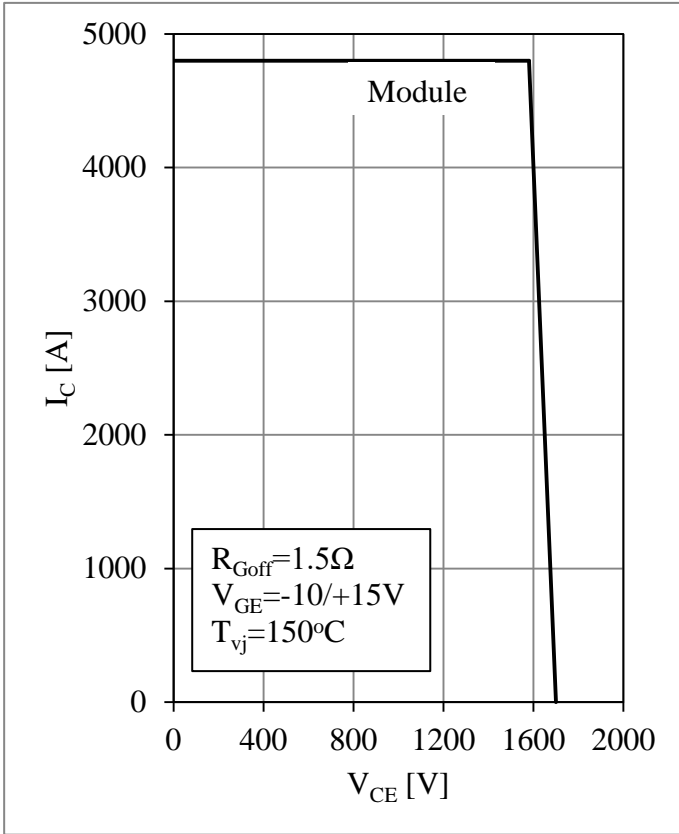


Fig 5. RBSOA

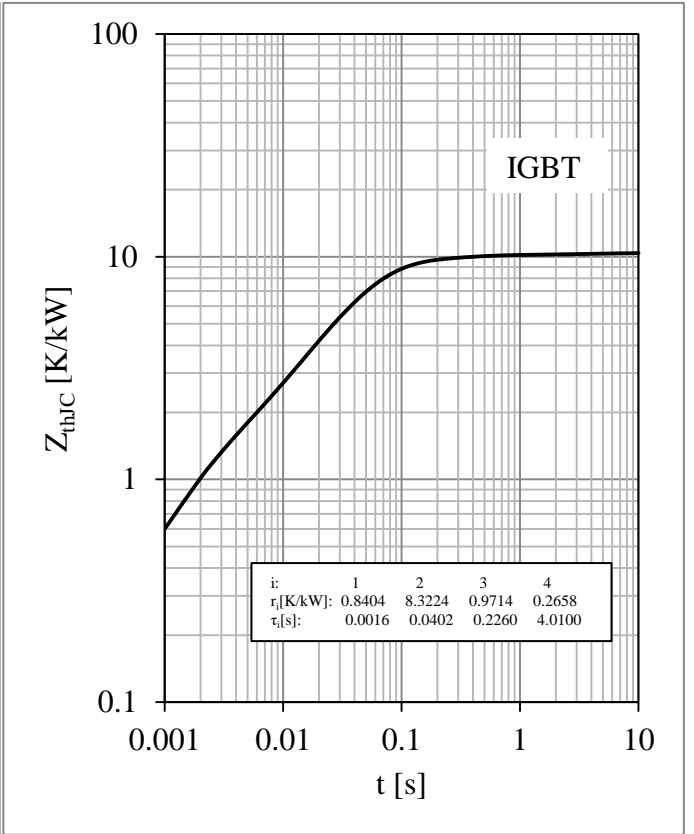


Fig 6. IGBT Transient Thermal Impedance

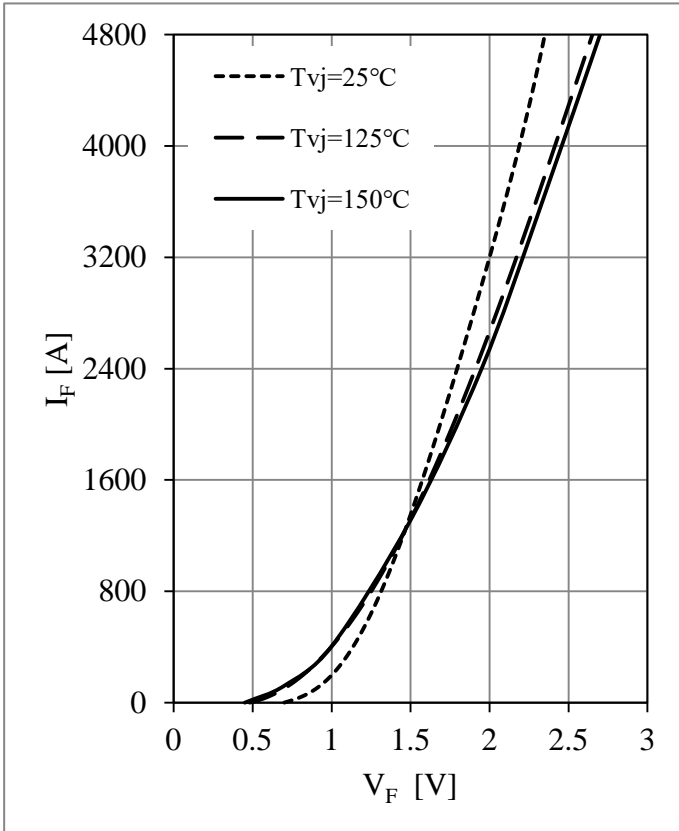


Fig 7. Diode Forward Characteristics

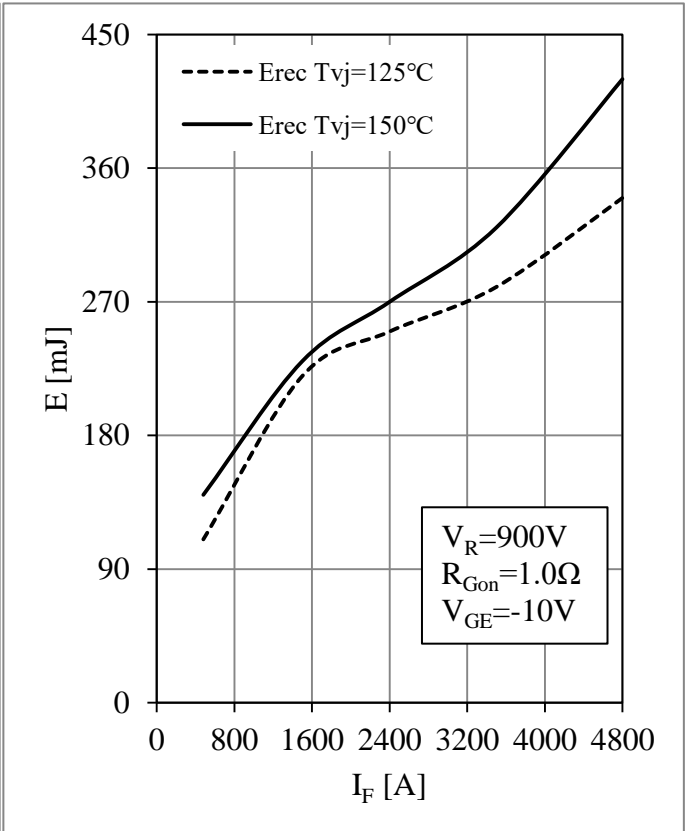


Fig 8. Diode Switching Loss vs.  $I_F$

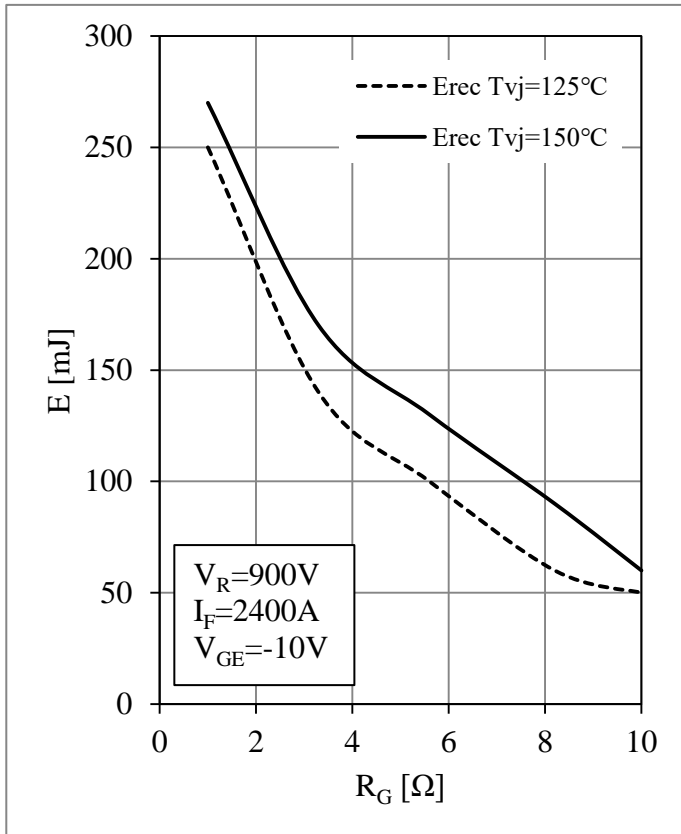


Fig 9. Diode Switching Loss vs.  $R_G$

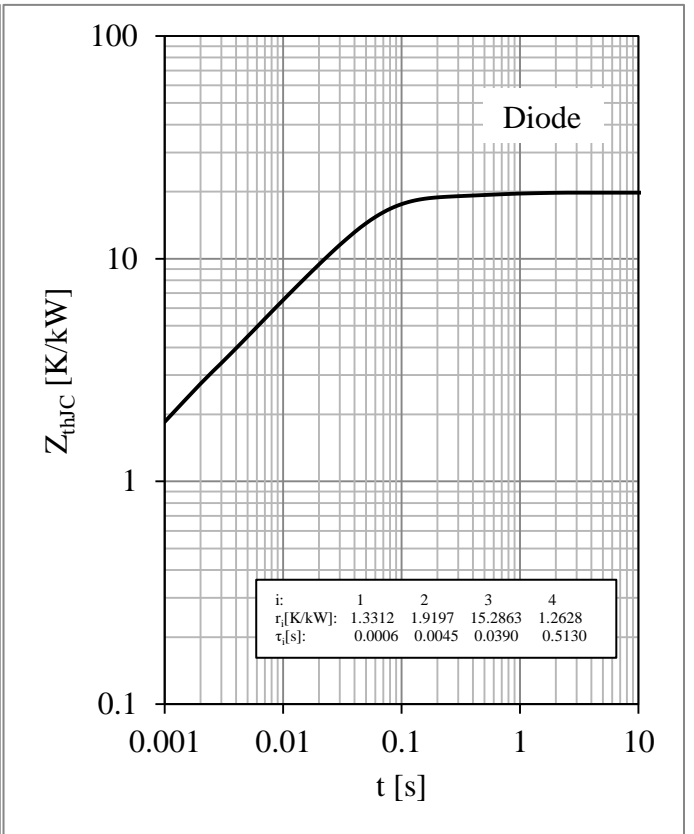
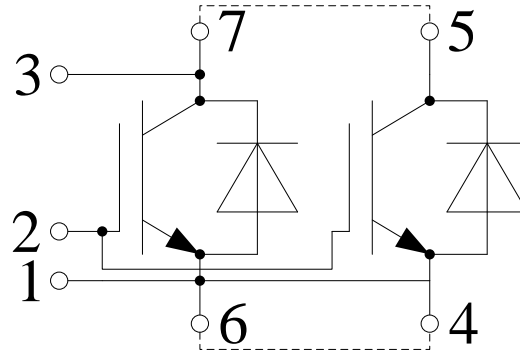


Fig 10. Diode Transient Thermal Impedance

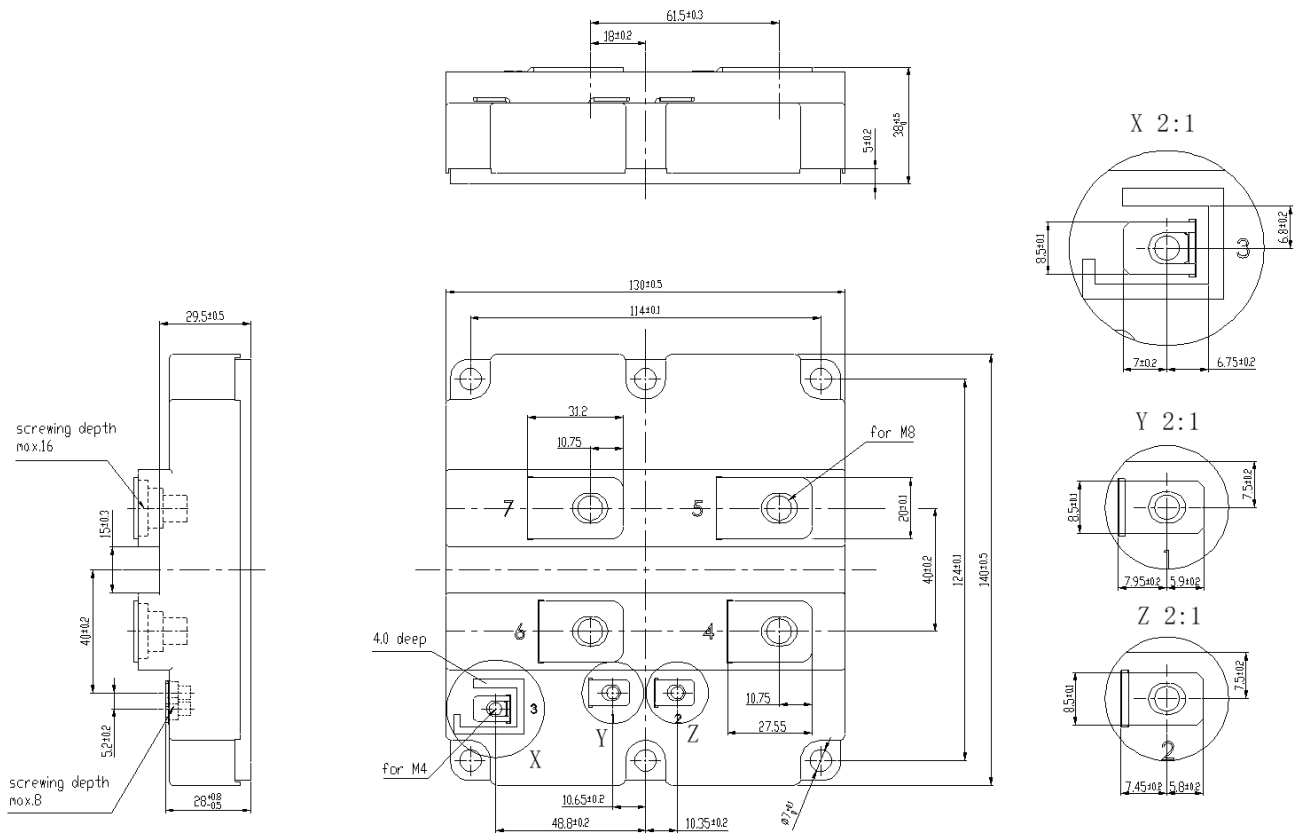
**Circuit Schematic**



external connection (to be done)

**Package Dimensions**

Dimensions in Millimeters





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